

DUAL DAMASCENE INTERCONNECT STRUCTURE USING LOW STRESS  
FLUOROSILICATE INSULATOR WITH COPPER CONDUCTORS

Abstract of the Disclosure

- 5       A metallization insulating structure, having  
a substrate;  
a substantially fluorine free insulating layer formed on the  
substrate, having a height,  $h_i$ ;  
a fluorine containing insulating layer formed on the  
10       substantially fluorine free insulating layer, having a  
height  $h_f$ .